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February 2008

74LVT2244, 74LVTH2244 Low Voltage Octal Buffer/Line Driver with 3-STATE Outputs and 25 Ω Series Resistors in the Outputs

Features

- Input and output interface capability to systems at 5V V_{CC}
- Equivalent 25Ω-Series resistors on outputs
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs (74LVTH2244), also available without bushold feature (74LVT2244)
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink -12mA/+12mA
- Latch-up performance exceeds 500mA
- ESD performance:
 - Human-body model > 2000V
 - Machine model > 200V
 - Charged-device model > 1000V

General Description

The LVT2244 and LVTH2244 are octal buffers and line drivers designed to be employed as memory address drivers, clock drivers and bus oriented transmitters or receivers which provides improved PC board density. The equivalent 25Ω -Series resistors helps reduce output overshoot and undershoot.

The LVTH2244 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs.

These octal buffers and line drivers are designed for low-voltage (3.3V) V_{CC} applications, but with the capability to provide a TTL interface to a 5V environment. The LVT2244 and LVTH2244 are fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining low power dissipation.

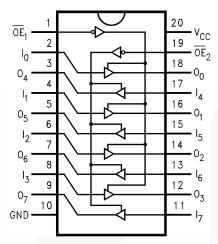
Ordering Information

Order Number	Package Number	Package Description			
74LVT2244WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide			
74LVT2244SJ	M20D	D-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide			
74LVT2244MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide			
74LVTH2244WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide			
74LVTH2244SJ	M20D	0-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide			
74LVTH2244MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide			

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

All packages are lead free per JEDEC: J-STD-020B standard.

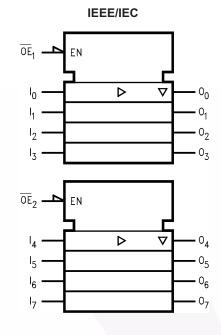
Connection Diagram



Pin Description

Pin Names	Description
$\overline{OE}_1, \overline{OE}_2$	3-STATE Output Enable Inputs
I ₀ –I ₇	Inputs
O ₀ –O ₇	Outputs

Logic Symbol



Truth Tables

Inp	uts	Outputs
OE ₁	I _n	(Pins 12, 14, 16, 18)
L	L	L
L	Н	Н
Н	Х	Z

Inp	uts	Outputs
OE ₂	In	(Pins 3, 5, 7, 9)
L	L	L
L	Н	Н
Н	X	Z

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating		
V _{CC}	Supply Voltage	-0.5V to +4.6V		
V _I	DC Input Voltage	-0.5V to +7.0V		
Vo	DC Output Voltage			
	Output in 3-STATE	-0.5V to +7.0V		
	Output in HIGH or LOW State ⁽¹⁾	-0.5V to +7.0V		
I _{IK}	DC Input Diode Current, V _I < GND			
I _{OK}	DC Output Diode Current, V _O < GND			
Io	DC Output Current, V _O > V _{CC}			
	Output at HIGH State	64mA		
	Output at LOW State	128mA		
I _{CC}	DC Supply Current per Supply Pin	±64mA		
I _{GND}	DC Ground Current per Ground Pin	±128mA		
T _{STG}	Storage Temperature	−65°C to +150°C		

Note:

1. IO Absolute Maximum Rating must be observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Units
V _{CC}	Supply Voltage	2.7	3.6	V
VI	Input Voltage	0	5.5	V
I _{OH}	HIGH-Level Output Current		-12	mA
I _{OL}	OL LOW-Level Output Current		12	mA
T _A	T _A Free-Air Operating Temperature		85	°C
Δt/ΔV	Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V	0	10	ns/V

DC Electrical Characteristics

					T _A = -4	10°C to +	85°C	
Symbol	Parame	ter	V _{CC} (V)	Conditions	Min.	Typ. ⁽²⁾	Max.	Units
V _{IK}	Input Clamp Diode V	oltage	2.7	$I_I = -18mA$			-1.2	V
V _{IH}	Input HIGH Voltage		2.7–3.6	$V_O \le 0.1V$ or	2.0			V
V _{IL}	Input LOW Voltage		2.7–3.6	$V_{O} \ge V_{CC} - 0.1V$			0.8	V
V _{OH}	Output HIGH Voltage	,	2.7–3.6	$I_{OH} = -100\mu A$	V _{CC} - 0.2			V
			3.0	$I_{OH} = -12mA$	2.0			
V _{OL}	Output LOW Voltage		2.7	$I_{OL} = 100 \mu A$			0.2	V
			3.0	I _{OL} = 12mA			0.8	
I _{I(HOLD)} ⁽³⁾	Bushold Input Minim	um Drive	3.0	$V_{I} = 0.8V$	75			μA
				V _I = 2.0V	-75]
I _{I(OD)} ⁽³⁾	Bushold Input Over-D	rive Current to	3.0	(4)	500			μA
	Change State			(5)	-500			1
I _I	Input Current		3.6	$V_{I} = 5.5V$			10	μA
		Control Pins	3.6	$V_I = 0V \text{ or } V_{CC}$			±1	1
	197	Data Pins	3.6	$V_I = 0V$			- 5	1
				$V_I = V_{CC}$			1	
I _{OFF}	Power Off Leakage C	Current	0	$0V \le V_I \text{ or } V_O \le 5.5V$	/		±100	μA
I _{PU/PD}	Power up/down 3-ST Output Current	ATE	0–1.5	$V_O = 0.5V$ to 3.0V, $V_I = GND$ or V_{CC}		\	±100	μA
I _{OZL}	3-STATE Output Lea	kage Current	3.6	$V_0 = 0.5V$			- 5	μA
I _{OZH}	3-STATE Output Lea	kage Current	3.6	$V_0 = 3.0V$			5	μA
I _{OZH} +	3-STATE Output Lea	kage Current	3.6	$V_{CC} < V_O \le 5.5V$			10	μA
I _{CCH}	Power Supply Currer	nt	3.6	Outputs HIGH			0.19	mA
I _{CCL}	Power Supply Currer	nt	3.6	Outputs LOW			5	mA
I _{CCZ}	Power Supply Current		3.6	Outputs Disabled			0.19	mA
I _{CCZ} +	Power Supply Current		3.6	$V_{CC} \le V_O \le 5.5V$, Outputs Disabled			0.19	mA
Δl _{CC}	Increase in Power Su	upply Current ⁽⁶⁾	3.6	One Input at V _{CC} – 0.6V, Other Inputs at V _{CC} or GN	ID		0.2	mA

Notes:

- 2. All typical values are at $V_{CC} = 3.3V$, $T_A = 25$ °C.
- 3. Applies to bushold versions only (74LVTH2244).
- 4. An external driver must source at least the specified current to switch from LOW-to-HIGH.
- 5. An external driver must sink at least the specified current to switch from HIGH-to-LOW.
- 6. This is the increase in supply current for each, input that is at the specified voltage level rather than V_{CC} or GND.

Dynamic Switching Characteristics⁽⁷⁾

			Conditions	T	A = 25°	С	
Symbol	Parameter	V _{CC} (V)	$C_L = 50 pF, R_L = 500 \Omega$	Min.	Тур.	Max.	Units
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3	(8)		0.8		V
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3	(8)		-0.8		V

Notes:

- 7. Characterized in SOIC package. Guaranteed parameter, but not tested.
- 8. Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

AC Electrical Characteristics

		$T_A = -40$ °C to +85°C, $C_L = 50$ pF, $R_L = 500$ Ω					
		V _{CC}	= 3.3V ±	0.3V	V _{CC} =	= 2.7V	
Symbol	Parameter	Min.	Typ. ⁽⁹⁾	Max.	Min.	Max.	Units
t _{PLH}	Propagation Delay Data to Output	1.0		4.4	1.0	5.3	ns
t _{PHL}		1.0		4.1	1.0	4.4	
t _{PZH}	Output Enable Time	1.0		5.9	1.0	7.7	ns
t _{PZL}		1.1		5.5	1.1	6.2	
t _{PHZ}	Output Disable Time	1.9		6.1	1.9	6.8	ns
t _{PLZ}		1.8		4.5	1.8	4.5	
toshl, toslh	Output to Output Skew ⁽¹⁰⁾			1.0		1.0	ns

Notes:

- 9. All typical values are at $V_{CC} = 3.3V$, $T_A = 25$ °C.
- 10. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Capacitance⁽¹¹⁾

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	$V_{CC} = 0V$, $V_I = 0V$ or V_{CC}	3	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.0V$, $V_{O} = 0V$ or V_{CC}	6	pF

Note:

11. Capacitance is measured at frequency f = 1MHz, per MIL-STD-883B, Method 3012.

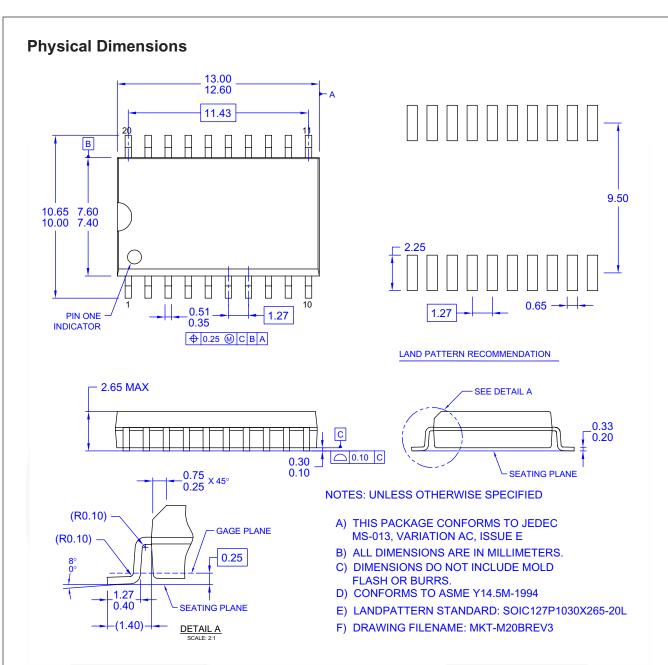
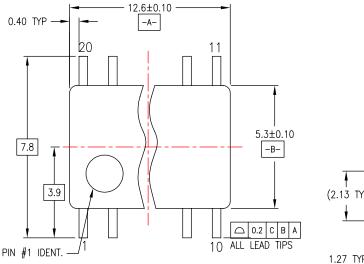


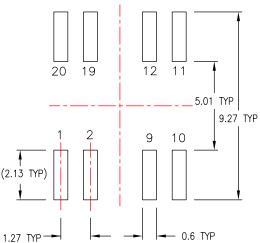
Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

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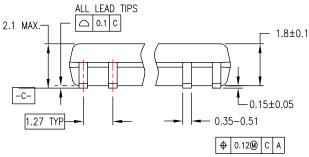
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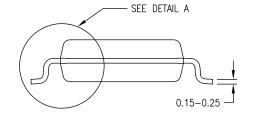
Physical Dimensions (Continued)





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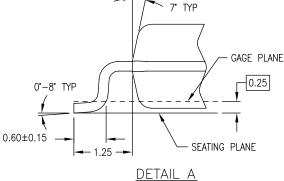




DIMENSIONS ARE IN MILLIMETERS

NOTES:

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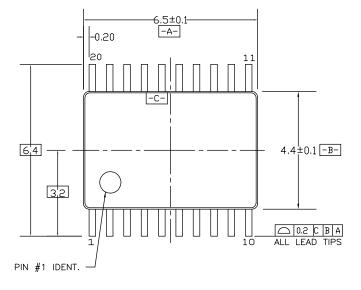
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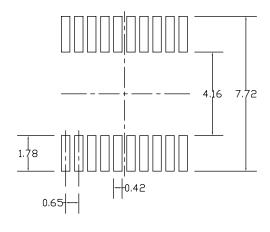
Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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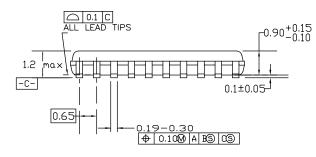
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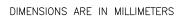
Physical Dimensions (Continued)





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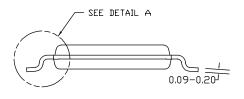


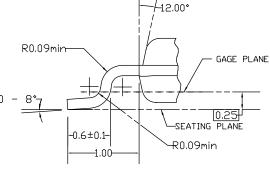


NOTES:

MTC20REVD1

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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.





DETAIL A

Figure 3. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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